



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

23-JUN-2003

SUBJECT: ON Semiconductor Final Product/Process Change Notification #12505

**TITLE: Qualification of Additional Assembly/Test Site for ON Semiconductor US8 PACKAGE,
Used for Minigate Devices**

EFFECTIVE DATE: 20-Aug-2003

AFFECTED CHANGE CATEGORY:
ON Semiconductor Assembly and Test Site

AFFECTED PRODUCT DIVISION: Logic Products Div

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Representative or Laura Rivers <S20636@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Representative
or Dianne Von Borstel <RPDR20@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Representative or John Miller <S20812@onsemi.com>

NOTIFICATION TYPE:
Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

To continuously improve and expand our manufacturing/test capacity, ON Semiconductor would like to announce the qualification of an additional assembly/test site for US8 Logic Standard Components devices. The additional site is ON Semiconductor's Seremban, Malaysia facility (SBN). Logic Minigate US8 devices are currently produced in Hana, Thailand. The Seremban site is ISO/QS9000 and TS16949 certified and is currently manufacturing Discrete and Logic devices in other packages. All physical, as well as electrical characteristics will not change and the reliability will continue to meet ON Semiconductor's high quality standards. This alternate site will allow ON Semiconductor to continue to meet the high demand for our US8 device families. The US8 lead finish will be available in tin/lead form or Pb Free. Pb Free US8 products are identified by adding a G suffix to the orderable part number.



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RELIABILITY DATA SUMMARY:

Device type: N27wz126US

Preconditioning 260 Deg c

| | HAST 96 Hrs | AC 96 hrs | TC 500 cyc | 1000 cyc |
|-----------|----------------|--------------|---------------|----------|
| Qual A | 0/84 | 0/84 | 0/84 | 0/84 |
| Qual B | 0/84 | 0/84 | 0/84 | 0/84 |
| Qual C | 0/84 | 0/84 | 0/84 | 0/84 |
| Control 1 | 0/84 | 0/84 | 0/84 | 0/84 |

Standard

| | HTS 504 hrs | 1008 hrs | HTOL 504 hrs | Solderability 260 Deg c |
|-----------|----------------|----------|-----------------|----------------------------|
| Qual A | 0/84 | 0/84 | 0/84 | 0/10 |
| Qual B | 0/84 | 0/84 | 0/84 | 0/10 |
| Qual C | 0/84 | 0/84 | 0/84 | 0/10 |
| Control 1 | 0/84 | 0/84 | 0/84 | 0/10 |

Wire Pull Test Results: The results for the wire pull test - 0/30 failures.

Ball Shear Test Results: The results for the ball shear test - 0/30 failures.

ELECTRICAL CHARACTERISTIC SUMMARY:

Electrical characterization has been completed on the designated qualification devices. These devices are representative of the entire family and will qualify the process. Datasheet specifications and electrical performance of the devices will remain unchanged. A full characterization report is available upon request.

CHANGED PART IDENTIFICATION:

Product with date code 8 (Aug, 2003) and forward may be from the SBN assembly site. The date code on SBN product is to the right of the device code in the same orientation. The date Code of the Hana product is rotated 90 degrees counterclockwise.

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

PART

NL17SZ74US
 NL17WZ74US
 NL27WZ00US
 NL27WZ02US
 NL27WZ08US
 NL27WZ125US
 NL27WZ126US
 NL27WZ32US
 NL27WZ86US
 NL37WZ04US
 NL37WZ06US
 NL37WZ07US
 NL37WZ14US
 NL37WZ16US
 NL37WZ17US
 NLAS1053US
 NLAS323US
 NLAS324US
 NLAS325US